MTM23123

Silicon P-channel MOSFET

For digital circuits

■ Features

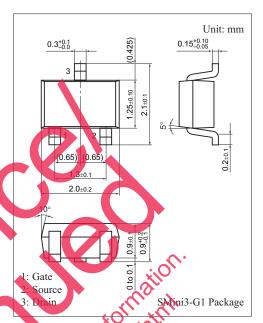
- Low voltage drive (2.5 V, 4 V)
- Realization of low on-resistance, using extremely fine process

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Drain-source surrender voltage	V _{DSS}	-20	V	
Gate-source surrender voltage	V _{GSS}	±10	V	
Drain current	I_D	-3.0	A	
Peak drain current *1	I_{DP}	-16	A	
Power dissipation *2	P_{D}	500	mW	
Channel temperature	T _{ch}	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

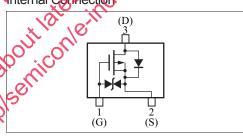
Note) *1: Pulse width $\leq 10 \mu s$, Duty Cycle $\leq 1\%$

*2: Measuring on ceramic substrate at 40 mm 38 mm × 0.1 mm Absolute maximum rating without heat sink for P_D is 150 mW



Marking Symbol. Bl

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■ Electrical Characteristics $T_a = 25^{\circ}C \rightarrow 3^{\circ}C$

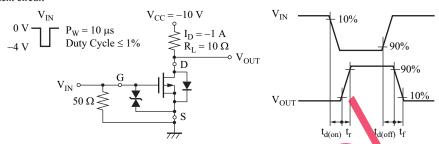
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Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Drain-source surrender voltage	V _{DSS}	$I_D = 0$ mA. $V_{OS} = 0$	-20			V	
Drain-source cutoff current	I_{DSS}	$V_{DS} = -20 V, V_{GS} = 0$			-1.0	μΑ	
Gate-source cutoff current	I_{GSS}	$V_{OS} = \pm 8 \text{ V}, V_{DS} = 0$			±10	μΑ	
Gate threshold voltage	NH X	$I_D = -1.0 \text{ mA}, V_{DS} = -10.0 \text{ V}$	-0.4	-0.85	-1.3	V	
Drain-source ON resistance *1	R _{DS(on)}	$I_D = -1 \text{ A}, V_{GS} = -4.0 \text{ V}$		40	55	mΩ	
		$I_D = -0.5 \text{ A}, V_{GS} = -2.5 \text{ V}$		45	70		
Forward transfer admittance *1	Y _{fs}	$I_D = -1.0 \text{ A}, V_{DS} = -10 \text{ V}, f = 1 \text{ kHz}$	3.5			S	
Short-circuit forward transfer capacitance (Common source)	C _{iss}			1000		pF	
Short-circuit output capacitance (Common source)	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		120		pF	
Reverse transfer capacitance (Common source)	C _{rss}			120		pF	
Turn-on delay time *2	t _{d(on)}	$V_{DD} = -10 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1 \text{ A}$		25		ns	
Rise time *2	t _r	$V_{DD} = -10 \text{ V}, V_{GS} = 0 \text{ V to } -4 \text{ V}, I_D = -1 \text{ A}$		25		ns	
Fall time *2	t _f	$V_{DD} = -10 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1 \text{ A}$		70		ns	
Turn-off delay time *2	t _{d(off)}	$V_{DD} = -10 \text{ V}, V_{GS} = -4 \text{ V to } 0 \text{ V}, I_D = -1 \text{ A}$		120		ns	

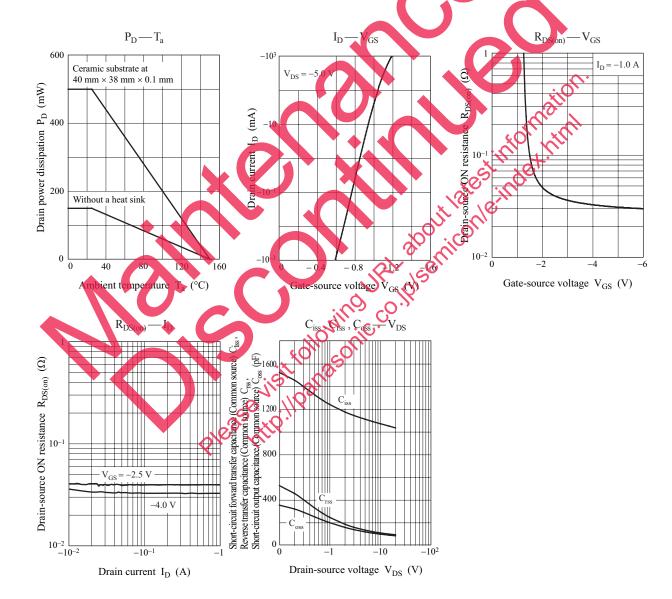
MTM23123 Panasonic

■ Electrical Characteristics (continued) $T_a = 25$ °C±3°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. *1: Pulse measurement: Pulse width < 300 μ s, Duty Cycle < 2.0%
 - *2: Measurement circuit





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